

Application No.: 09/741,684

Amendment and Response dated: August 25, 2006

Reply to Office Action dated: April 25/2006

AMENDMENTS TO THE CLAIMS

1-18 (Cancelled)

19. (Previously Presented) A suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and

a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad, wherein the slider bonding pad enables the reuse of the suspension by removing the connection between a slider and the slider bonding pad with heat treatment.

20. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is solder.

21. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is a conductive polymer.

22. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is an adhesive.

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23. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is a film.
24. (Previously Presented) The suspension as claimed in claim 20, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .
25. (Currently Amended) A suspension comprising:
a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and
a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad wherein bonding substance of the suspension further comprises several bonding bumps for bonding the suspension and a slider connection circuit.
26. (Previously Presented) The suspension as claimed in claim 25, wherein said bonding substance is solder.
27. (Previously Presented) The suspension as claimed in claim 25, wherein said bonding substance is a conductive polymer.

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28. (Previously Presented) The suspension as claimed in claim 25, wherein said bonding substance is an adhesive.

29. (Previously Presented) The suspension as claimed in claim 25, wherein said bonding substance is a film.

30. (Currently Amended) The suspension as claimed in ~~claim 26~~, claim 25, wherein the bonding bumps ~~have~~ are solder bonding bumps, and wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .